Reply to Office Action of December 12, 2006

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1 – 9: Cancelled

10. (currently amended) A circuit arrangement for bridging high voltages using a switching signal, comprising:

a voltage transmitter with first and second terminals for a low voltage;

a voltage receiver with third and fourth terminals for a higher voltage relative to the low voltage between the first and second terminals, wherein the voltage transmitter and the voltage receiver each comprise a first inverter circuit and a second inverter circuit,

wherein the inverter circuits of the voltage transmitter are connected between the first and second terminals and the inverter circuits of the voltage receiver are connected between the third and fourth terminals,

wherein an <u>output</u> <u>outlet</u> of the first inverter circuit of the voltage transmitter is connected via a first capacitor as a high voltage capacitor with an <u>input</u> inlet of the second inverter circuit of the voltage receiver and an <u>output</u> outlet of the first inverter circuit of the voltage receiver, and an <u>output</u> outlet of the second inverter circuit of the voltage transmitter is connected via a second capacitor as a high voltage capacitor with an <u>input</u> inlet of the first inverter circuit of the voltage receiver and an output outlet of the second inverter circuit of the voltage receiver,

wherein the <u>inputs</u> inlets of the first inverter circuit and the second inverter circuit, respectively, of the voltage transmitter are a non-inverted and an

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inverted input inlet, and wherein the outputs outlets of the first inverter circuit and the

second inverter circuit, respectively, of the voltage receiver represent output outlet

nodes,

wherein the circuit arrangement for bridging high voltage with a switching

signal is realized as an integrated semi-conductor circuit made with semi-conductor

processes with CMOS circuits as the inverter circuits or a stack of layers with

alternating layers of circuit stopper implantation, field oxide, poly-silicon, CVD-oxide,

metal, CVD-oxide, metal, and so on, whereby the layers are electrically alternatingly

connected, as the first capacitor and as the second capacitor, respectively, as high

voltage capacitors.

11. (currently amended) The circuit arrangement of claim 10, wherein a

third inverter circuit is connected between the first and second terminals, wherein an

output outlet of the third inverter circuit is connected with the input inlet of the first

inverter circuit of the voltage transmitter, wherein the input inlet of the third inverter

circuit is connected with the input inlet of the second inverter circuit of the voltage

transmitter, and wherein the input inlet of the third inverter circuit is connected with a

terminal IN as the input inlet of the circuit arrangement for bridging high voltages with

a switching signal.

12. (currently amended) The circuit arrangement of claim 10, wherein a

fourth inverter circuit and a fifth inverter circuit are connected between the third and

fourth terminals, wherein an input inlet of the fourth inverter circuit is connected with

the input inlet of the first inverter circuit of the voltage receiver, wherein an input inlet

of the fifth inverter circuit is connected with the input inlet of the second inverter

circuit of the voltage receiver, wherein an output outlet of the fourth inverter circuit is

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connected with a terminal OUT1 as the first output outlet of the voltage receiver, and

wherein an output outlet of the fifth inverter circuit is connected with a terminal OUT2

as the second output outlet of the voltage receiver.

13. (currently amended)The circuit arrangement of claim 11 10, wherein a

sixth inverter circuit and a seventh inverter circuit are connected between the first

and second terminals, wherein an input inlet of the seventh inverter circuit is

connected with the input inlet of the third inverter circuit and with a terminal IN as the

input inlet of the circuit arrangement for bridging high voltages with a switching

signal, wherein an output outlet of the seventh inverter circuit is connected with an

input inlet of the sixth inverter circuit, and wherein an output outlet of the sixth

inverter circuit is connected with the input inlet of the second inverter circuit of the

voltage transmitter.

14. (previously presented) The circuit arrangement of claim 10, wherein an

inverter circuit comprises two complementary transistors connected in series.

15. (currently amended) The circuit arrangement of claim 10, wherein the

first capacitor and the second capacitor are connected between the voltage

transmitter and the voltage receiver in such a way that the first capacitor and the

second capacitor, respectively, are charged as high voltage capacitors to voltage

differential to be overcome between the voltage transmitter and the voltage receiver

and the charges of the first capacitor and second capacitor subsequently vary at a

value $\Delta Q = C \times (Vdd - Vss)$ for signal transmission, wherein power consumption of

the circuit arrangement for bridging high voltages with a switching signal is

independent from the voltage differential to be overcome between the voltage

transmitter and the voltage receiver, and wherein simultaneously, an the applied

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differential principle in which C1 is charged at ΔQ, C2 is discharged at ΔQ, and vice versa guarantees a high signal-to-noise ratio relative to <u>push-pull</u> push-push interference signals.

- 16. (canceled)
- 17. (previously presented) The circuit arrangement of claim 10, wherein the voltage transmitter is one region or multiple regions of a semi-conductor chip, wherein the first capacitor is one region and the second capacitor is one region of the semi-conductor chip, wherein the voltage receiver is one region of the semi-conductor chip, wherein at least the region of the voltage transmitter and of the voltage receiver, respectively, is surrounded by a trench for voltage isolation.
- 18. (previously presented) The circuit arrangement of claim 10, wherein the circuit arrangement for bridging high voltages with a switching signal is realized as integrated semi-conductor circuits made with semi-conductor processes for integrated high voltage circuits with any isolation for the voltage transmitter, the high voltage capacitors, and the voltage receiver.